October 1998

SED1353 GRAPHICS LCD CONTROLLER
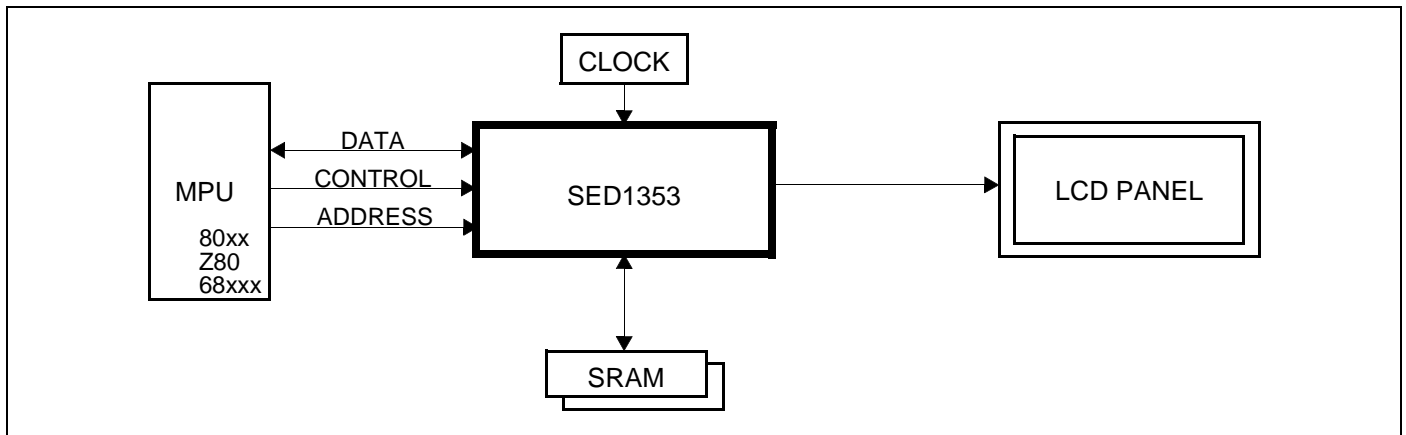
■ DESCRIPTION

The SED1353 is a dot matrix graphic LCD controller supporting resolutions up to 1024x1024. It is capable of displaying a maximum of 256 simultaneous colors out of a possible 4096 or 16 gray shades. Design flexibility allows the SED1353 to interface to either an MC68000 family microprocessor or an 8/16-bit MPU/bus with minimum external logic. The Static RAM (SRAM) interface used for the display buffer is optimized for speed and performance, supporting up to 128K bytes.

Two power save modes, combined with operating voltages of 2.7 volts through 5.5 volts, allow for a wide range of applications while providing minimum power consumption.

■ FEATURES

- pin compatible with the SED1352
- 16-bit 16 MHz MC68xxx MPU interface
- 8/16-bit MPU interface controlled by a READY (or WAIT#) signal
- option to use built-in index register or direct-mapping to access one of sixteen internal registers
- 2-terminal crystal or external oscillator support
- 8/16-bit SRAM interface configurations
- split screen display support allowing two different images to be simultaneously displayed
- virtual display support (displays images larger than the panel size through the use of panning)
- display modes:
    black-and-white display
    2/4 bits per pixel, 4/16-level gray-scale display
    2/4/8 bits per pixel, 4/16/256-level color display
- two software power-save modes

- low power consumption
- display memory interface:
    128K bytes using one 64Kx16 SRAMs
    128K bytes using two 64Kx8 SRAMs
    64K bytes using two 32Kx8 SRAMs
    40K bytes using one 8Kx8 and one 32Kx8 SRAM
    32K bytes using one 32Kx8 SRAM
    16K bytes using two 8Kx8 SRAMs
    8K bytes using one 8Kx8 SRAM
- LCD panel configurations:
    single-panel, single-drive passive display
    dual-panel, dual-drive passive display
- maximum number of vertical lines:
    1,024 lines (single-panel, single-drive display)
    2,048 lines (dual-panel, dual-drive display)
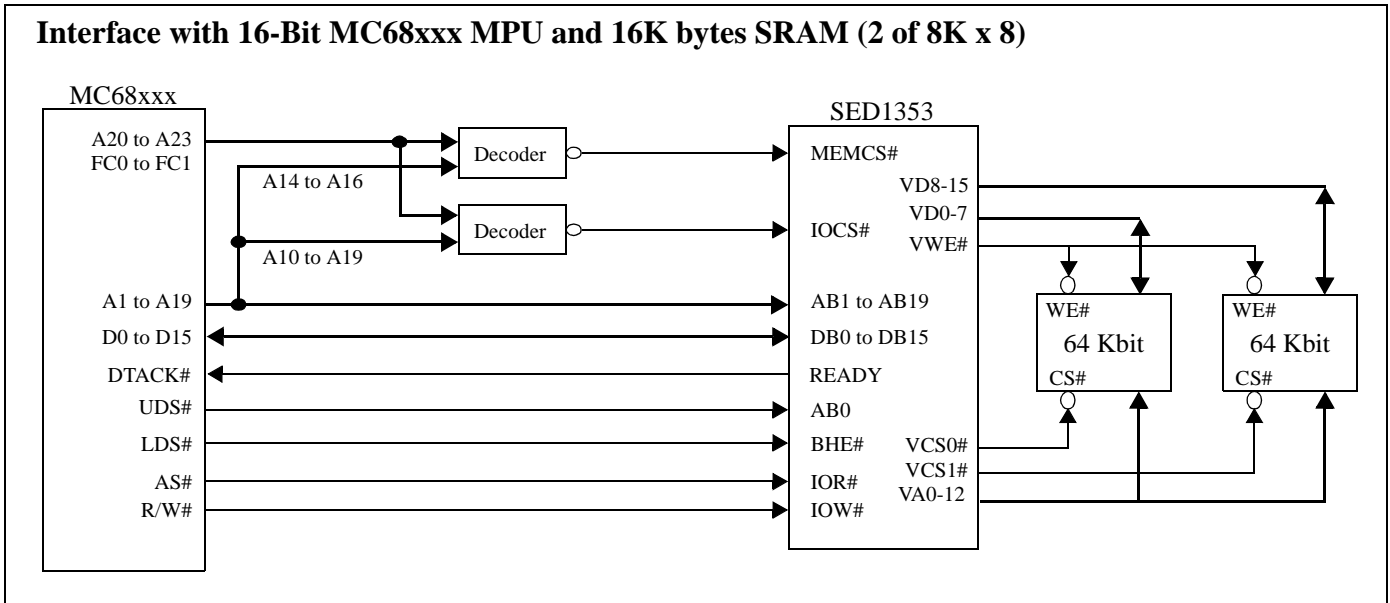- QFP5-100-S2 package (F0A)
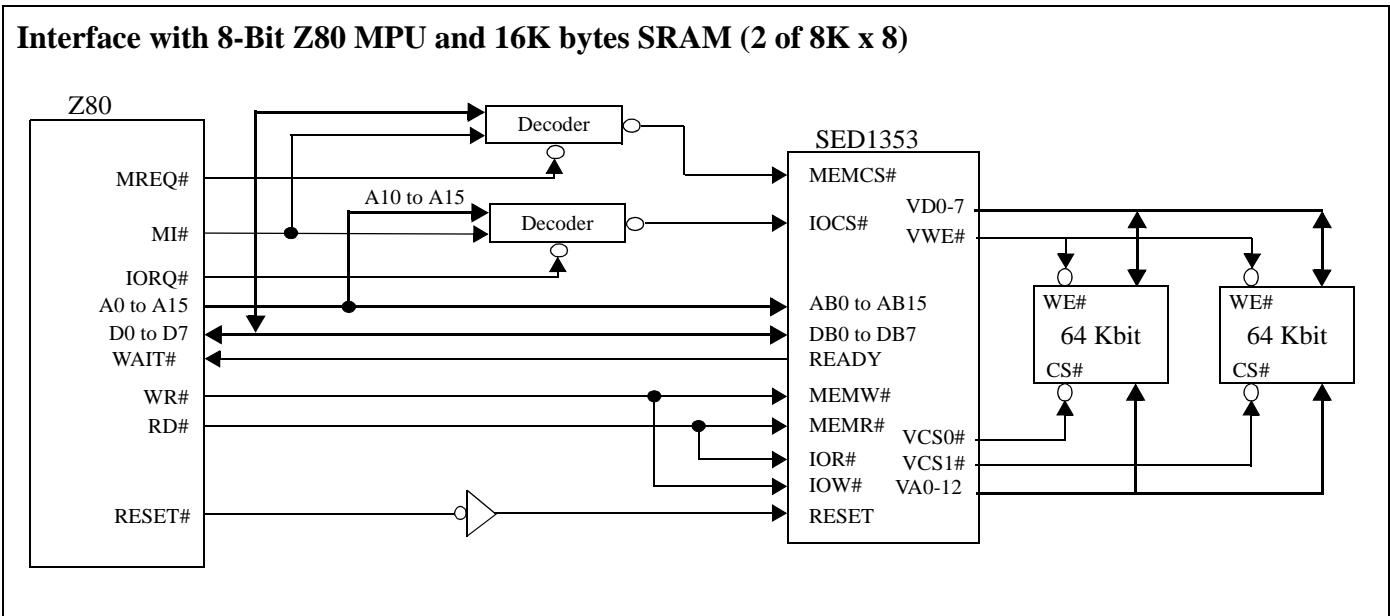- QFP15-100-STD package (F1A)

■ SYSTEM BLOCK DIAGRAM

■ INTERFACE OPTIONS

Interface with 16-Bit MC68xxx MPU and 16K bytes SRAM (2 of 8K x 8)

MC68xxx

|	
A20 to A23	
FC0 to FC1	
A14 to A16	Decoder
A10 to A19	Decoder
A1 to A19	
D0 to D15	
DTACK#	
UDS#	
LDS#	
AS#	
R/W#	

SED1353

MEMCS#
VD8-15
VD0-7
IOCS#
VWE#
AB1 to AB19
DB0 to DB15
READY
AB0
BHE#   VCS0#
IOR#   VCS1#
IOW#   VA0-12

WE#
64 Kbit
CS#

WE#
64 Kbit
CS#

Note: Example implementation, actual may vary.

Interface with 8-Bit Z80 MPU and 16K bytes SRAM (2 of 8K x 8)

Z80

	Decoder
MREQ#	
MI#	A10 to A15 Decoder
IORQ#	
A0 to A15	
D0 to D7	
WAIT#	
WR#	
RD#	
RESET#	

SED1353

MEMCS#
VD0-7
IOCS#
VWE#
AB0 to AB15
DB0 to DB7
READY
MEMW#
MEMR#
IOR#   VCS0#
IOW#   VCS1#
RESET   VA0-12
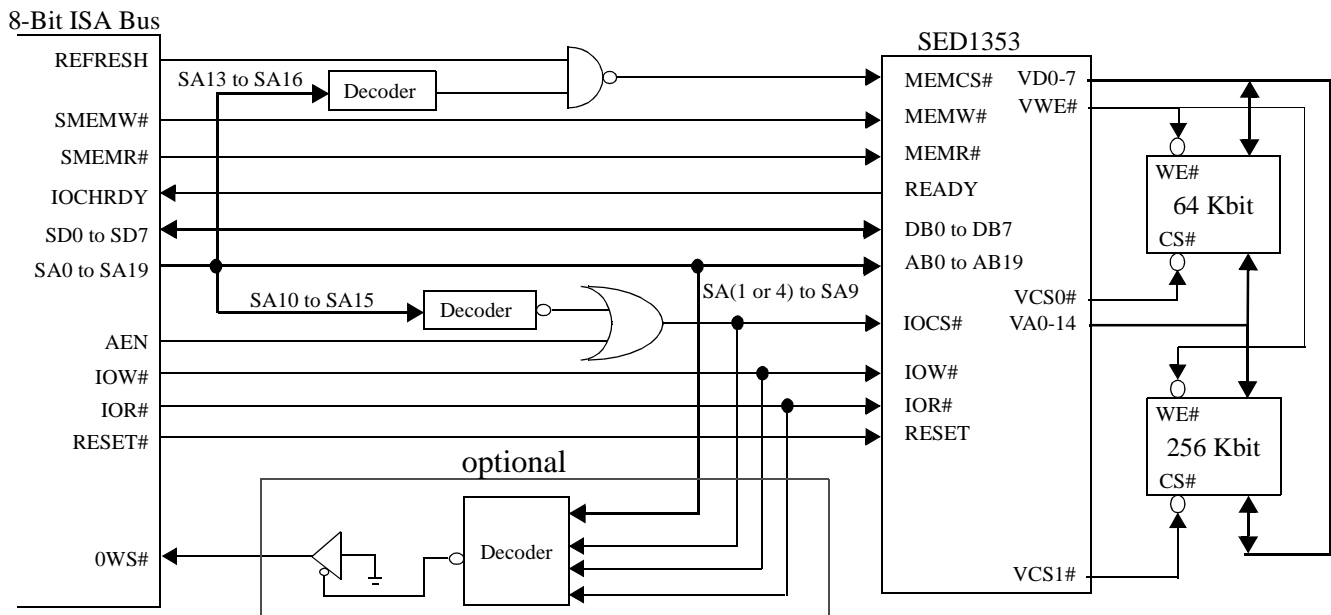
WE#
64 Kbit
CS#

WE#
64 Kbit
CS#

Note: Example implementation, actual may vary.

Interface with 16-Bit 8086 MPU and 64K bytes SRAM (2 of 32K x 8)
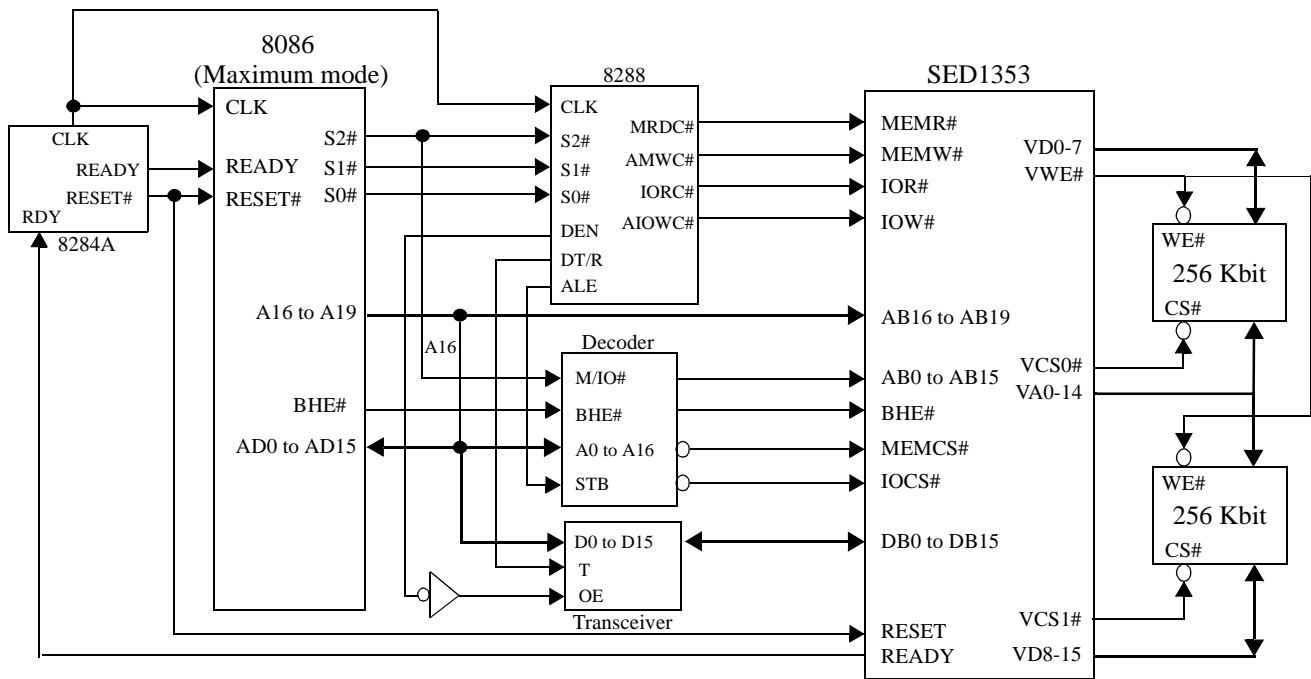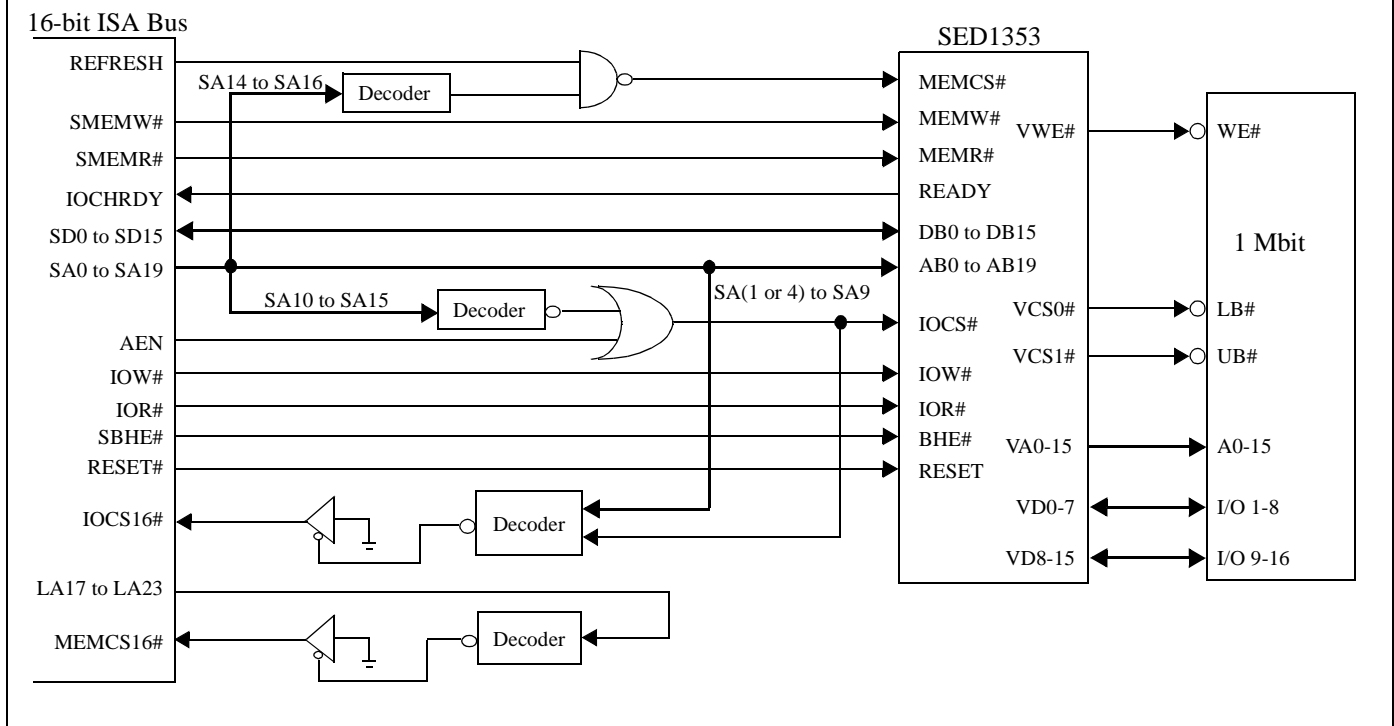

Note: Example implementation, actual may vary.

Interface with 8-Bit ISA Bus and 40K bytes SRAM (1 of 8K x 8 and 1 of 32K x 8)

Note: Example implementation, actual may vary.

Interface with 16-Bit ISA Bus and 128K bytes SRAM (1 of 128K x 8)


Note: Example implementation, actual may vary.

■ SUPPORTED RESOLUTIONS

Display RAM	Example Display Size				SRAM Type	CPU Interface	SRAM Interface
	Monochrome	4 Grays/Colors	16 Grays/Colors	256 Colors[a]			
	X Y	X Y	X Y	X Y			
8K byte	320 x 200	256 x 128	128 x 128	—	1 of 8Kx8	8-bit	8-bit
16K byte	512 x 256	320 x 200	200 x 160	160 x 100[a]	2 of 8Kx8	8-bit	8-bit/16-bit
						16-bit	16-bit
32K byte	512 x 512	512 x 256	256 x 256	192 x 100[a]	1 of 32Kx8	8-bit	8-bit
40K byte	1024 x 320	512 x 320	320 x 256	320 x 128[a]	1 of 8Kx8 and 1 of 32Kx8	8-bit	8-bit
64K byte	1024 x 512	512 x 512	512 x 256	256 x 256[a]	2 of 32Kx8	8-bit	8-bit/16-bit
						16-bit	16-bit
128K byte	1024 x 1024	1024 x 512	512 x 512	512 x 256[a]	1 of 64Kx16	16-bit	16-bit
					2 of 64Kx8	16-bit	16-bit

a. 256 colors must use 16-bit SRAM interface

The above listed display sizes are examples based on bits/pixel and available memory.

■ BLOCK DIAGRAM
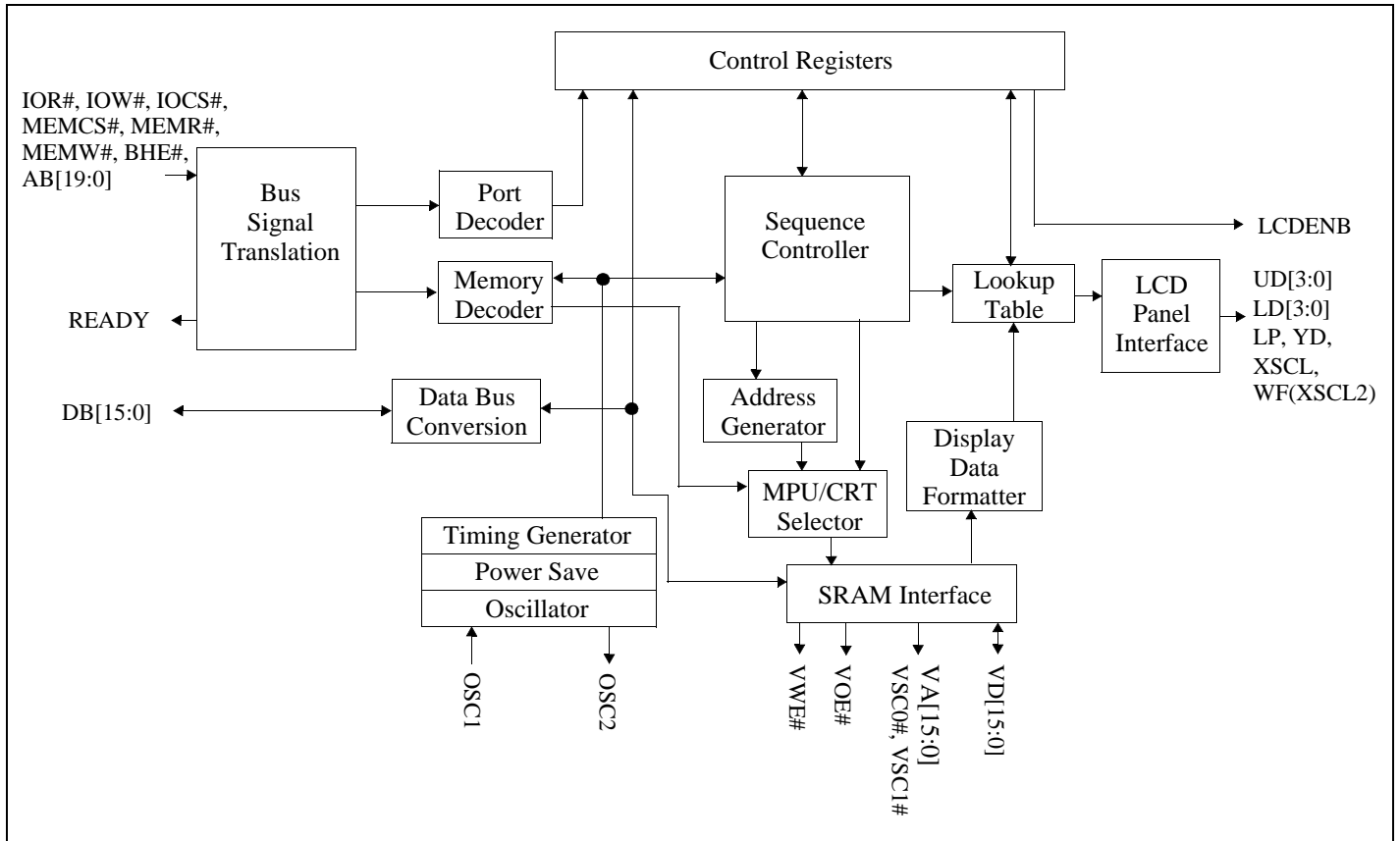
■ FUNCTIONAL BLOCK DESCRIPTION

Bus Signal Translation

According to configuration setting VD2, Bus Signal Translation translates either MC68000 type MPU signals or Ready type MPU signals to internal bus interface signals.

Control Registers

The Control Register contains 16 internal control and configuration registers. These registers can be accessed by either direct-mapping or using the built-in internal index register.

Sequence Controller

The Sequence Controller generates horizontal and vertical display timings according to the configuration registers settings.

LCD Panel Interface

The LCD Panel Interface performs frame rate modulation and output data pattern formatting for both passive monochrome and passive color LCD panels.

Look-Up Table

The Look-Up Table contains three 16x4-bit wide palettes. In gray shade modes, the "green" palette can be configured for the re-mapping of 16 possible shades of gray. In color modes, all three palettes can be configured for the re-mapping of 4096 possible colors.

Port Decoder

According to configuration settings VD1, VD12 - VD4, IOCS# and address lines AB9-1, the Port Decoder validates a given I/O cycle.

Memory Decoder

According to configuration settings VD15 - VD13, MEMCS# and address lines AB19-17, the Memory Decoder validates a given memory cycle.

Data Bus Conversion

According to configuration setting VD0, Data Bus Conversion maps the external data bus, either 8-bit or 16-bit, into the internal odd and even data bus.

Address Generator

The Address Generator generates display refresh addresses to be used to access display memory.

MPU / CRT Selector

The MPU / CRT Selector grants access to the display memory from either the MPU or the display refresh circuitry.

Display Data Formatter

The Display Data Formatter reads in the display data from the display memory and outputs the correct format for all supported gray shade and color selections.

Clock Inputs / Timing

Clock Inputs / Timing generates the internal master clock according to gray-level / color selected and display memory interface.The master clock (MCLK) can be:
- MCLK = input clock
- MCLK = 1/2 input clock
- MCLK = 1/4 input clock.

Pixel clock = input clock = f_{OSC}.

SRAM Interface

The SRAM Interface generates the necessary signals to interface to the Display Memory (SRAM).

■ DC SPECIFICATIONS

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DD}	Supply Voltage	V_{SS} - 0.3 to + 6.0	V
V_{IN}	Input Voltage	V_{SS} - 0.3 to V_{DD} + 0.5	V
V_{OUT}	Output Voltage	V_{SS} - 0.3 to V_{DD} + 0.5	V
T_{STG}	Storage Temperature	-65 to 150	° C
T_{SOL}	Solder Temperature/Time	260 for 10 sec. max at lead	° C

Recommended Operating Conditions

Symbol	Parameter	Condition	Min	Typ	Max	Units
V_{DD}	Supply Voltage	V_{SS} = 0 V	2.7	3.0/3.3/5.0	5.5	V
V_{IN}	Input Voltage		V_{SS}	--	V_{DD}	V
I_{OPR}	Operating Current	f_{OSC} = 6 MHz 256 colors		4.5/5.0/11		mA
T_{OPR}	Operating Temperature		-40	25	85	° C
P_{TYP}	Typical Active Power Consumption	f_{OSC} = 6 MHz 256 colors		13.5/16.5/55		mW

Input Specifications

Symbol	Parameter	Condition	Min	Typ	Max	Units
V_{IL}	Low Level Input Voltage	V_{DD} = 4.5V V_{DD} = 3.0V V_{DD} = 2.7V			0.8 0.4 0.3	V
V_{IH}	High Level Input Voltage	V_{DD} = 5.5V V_{DD} = 3.6V V_{DD} = 3.3V	2.0 1.3 1.2			V
V_{T+}	Positive-going Threshold	V_{DD} = 5.0 V_{DD} = 3.3 V_{DD} = 3.0			2.4 1.4 1.3	V
V_{T-}	Negative-going Threshold	V_{DD} = 5.0 V_{DD} = 3.3 V_{DD} = 3.0	0.6 0.5 0.4			V
V_H	Hysteresis Voltage	V_{DD} = 5.0 V_{DD} = 3.3 V_{DD} = 3.0	0.1 0.1 0.1			V
I_{IZ}	Input Leakage Current	--	-1		1	µA
C_{IN}	Input Pin Capacitance	f =1 MHz, V_{DD}= 0V			12	pF
R_{PD}	Pull Down Resistance	V_{DD} = 5.0V $V_I = V_{DD}$	50	100	200	kΩ
R_{PD}	Pull Down Resistance	V_{DD} = 3.3V $V_I = V_{DD}$	90	180	360	kΩ
R_{PD}	Pull Down Resistance	V_{DD} = 3.0V $V_I = V_{DD}$	100	200	400	kΩ

Output Specifications

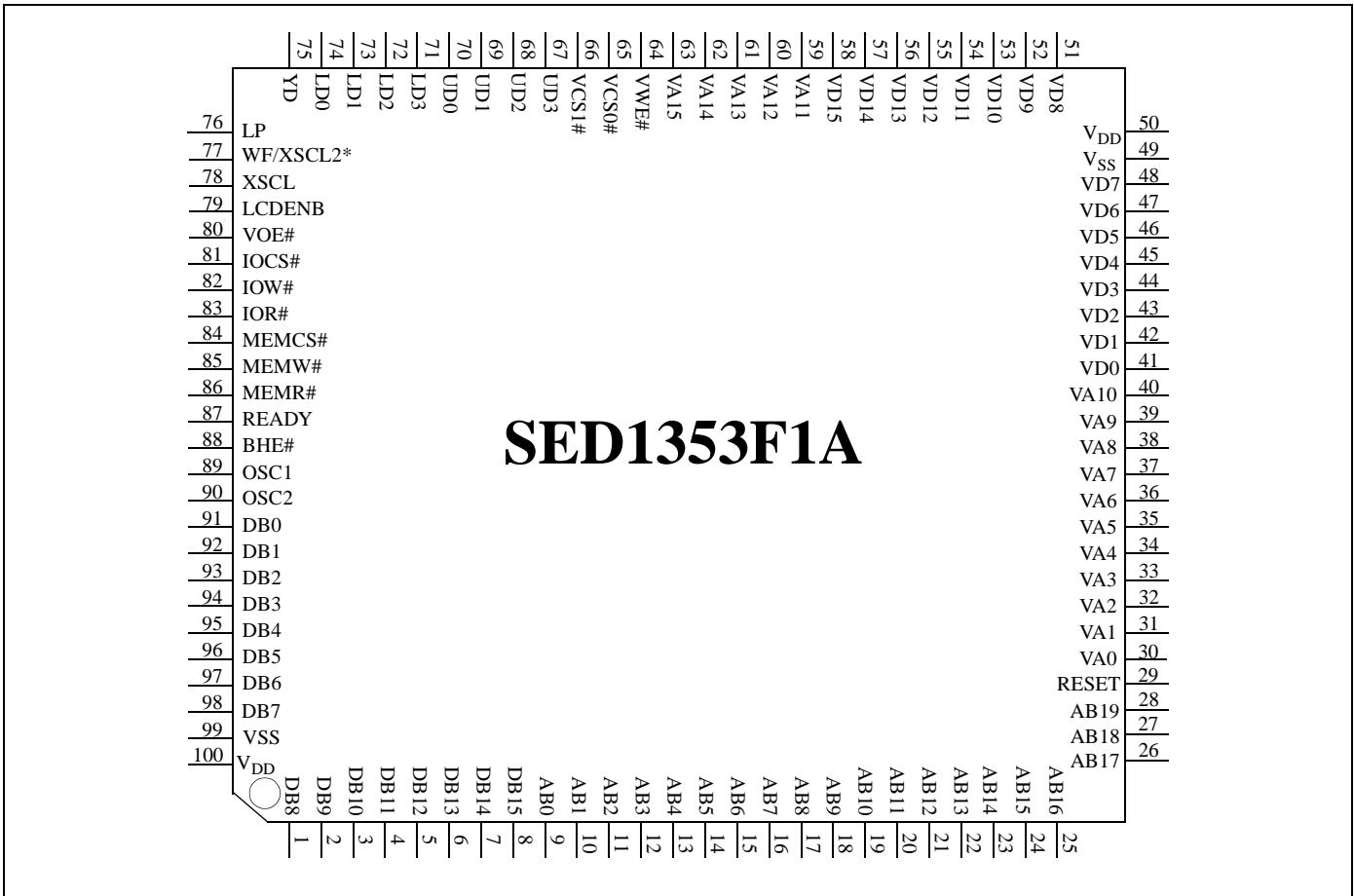| Symbol	Parameter	Condition	Min	Typ	Max	Units
V_{OL} (5.0V)	Low Level Output Voltage Type 1 - TS1D2, CO1 Type 2 - TS2, CO2 Type 3 - TS3, CO3, CO3S	V_{DD} = Min I_{OL} = 4 mA I_{OL} = 8 mA I_{OL} = 12 mA			0.4	V
V_{OL} (3.3V)	Low Level Output Voltage Type 1 - TS1D2, CO1 Type 2 - TS2, CO2 Type 3 - TS3, CO3, CO3S	V_{DD} = Min I_{OL} = 2 mA I_{OL} = 4 mA I_{OL} = 6 mA			0.3	V
V_{OL} (3.0V)	Low Level Output Voltage Type 1 - TS1D2, CO1 Type 2 - TS2, CO2 Type 3 - TS3, CO3, CO3S	V_{DD} = Min I_{OL} = 1.8 mA I_{OL} = 3.5 mA I_{OL} = 5 mA			0.3	V
V_{OH} (5.0V)	High Level Output Voltage Type 1 - TS1D2, CO1 Type 2 - TS2, CO2 Type 3 - TS3, CO3, CO3S	V_{DD} = Min I_{OH} = -4 mA I_{OH} = -8mA I_{OH} = -12 mA	V_{DD}-0.4			V
V_{OH} (3.3V)	Low Level Output Voltage Type 1 - TS1D2, CO1 Type 2 - TS2, CO2 Type 3 - TS3, CO3, CO3S	V_{DD} = Min I_{OL} = -2 mA I_{OL} = -4 mA I_{OL} = -6 mA	V_{DD}-0.3			V
V_{OH} (3.0V)	High Level Output Voltage Type 1 - TS1D2, CO1 Type 2 - TS2, CO2 Type 3 - TS3, CO3, CO3S	V_{DD} = Min I_{OH} = -1.8 mA I_{OH} = -3.5 mA I_{OH} = -5 mA	V_{DD}-0.3			V
I_{OZ}	Output Leakage Current	--	-1		1	μA
C_{OUT}	Output Pin Capacitance	f =1 MHz, V_{DD}= 0V			12	pF
C_{BID}	Bidirectional Pin Capacitance	f =1 MHz, V_{DD}= 0V			12	pF

■ SED1353F0A PIN OUT
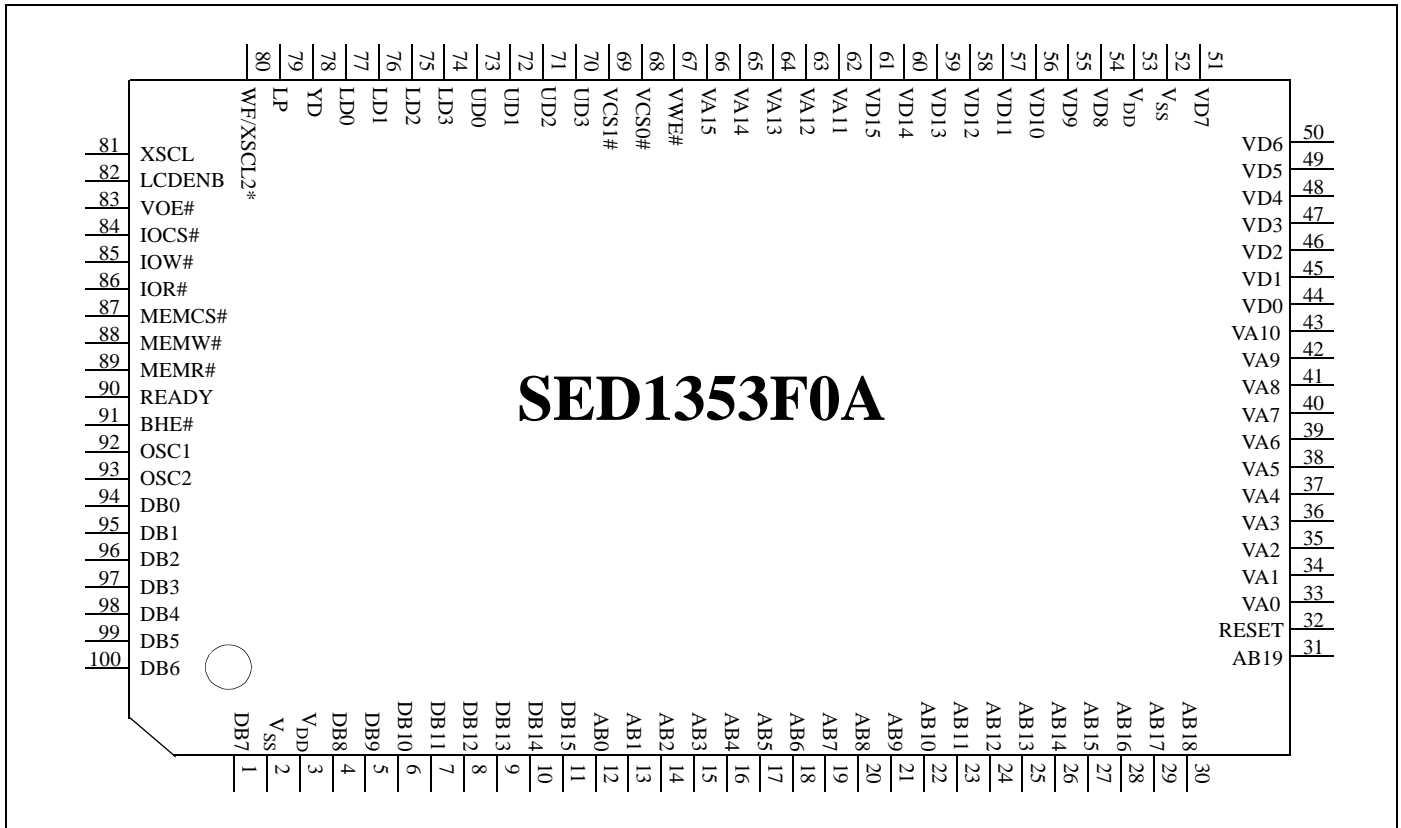
SED1353F0A

* Pin 80 = WF in all display modes except format 1 for 8-bit single color panel.
* Pin 80 = XSCL2 in format 1 for 8-bit single color panel.
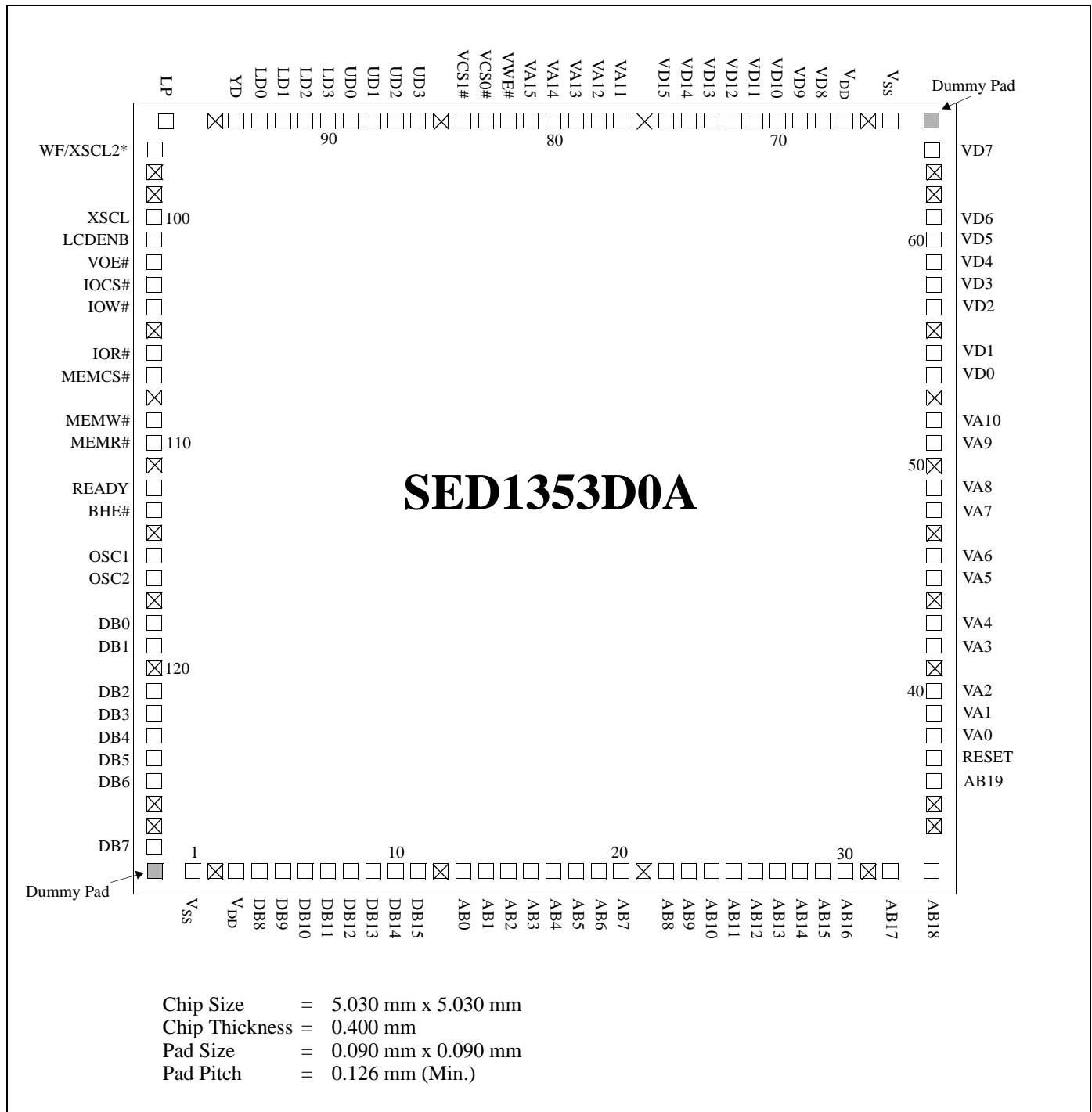
■ **SED1353F1A PIN OUT**

SED1353F1A

Top pins (left to right, 75 to 51): YD, LD0, LD1, LD2, LD3, UD0, UD1, UD2, UD3, VCS1#, VCS0#, VWE#, VA15, VA14, VA13, VA12, VA11, VD15, VD14, VD13, VD12, VD11, VD10, VD9, VD8

Left pins (top to bottom, 76 to 100):
76 LP
77 WF/XSCL2*
78 XSCL
79 LCDENB
80 VOE#
81 IOCS#
82 IOW#
83 IOR#
84 MEMCS#
85 MEMW#
86 MEMR#
87 READY
88 BHE#
89 OSC1
90 OSC2
91 DB0
92 DB1
93 DB2
94 DB3
95 DB4
96 DB5
97 DB6
98 DB7
99 VSS
100 V$_{DD}$

Right pins (top to bottom, 50 to 26):
50 V$_{DD}$
49 V$_{SS}$
48 VD7
47 VD6
46 VD5
45 VD4
44 VD3
43 VD2
42 VD1
41 VD0
40 VA10
39 VA9
38 VA8
37 VA7
36 VA6
35 VA5
34 VA4
33 VA3
32 VA2
31 VA1
30 VA0
29 RESET
28 AB19
27 AB18
26 AB17

Bottom pins (left to right, 1 to 25): DB8, DB9, DB10, DB11, DB12, DB13, DB14, DB15, AB0, AB1, AB2, AB3, AB4, AB5, AB6, AB7, AB8, AB9, AB10, AB11, AB12, AB13, AB14, AB15, AB16

* Pin 77 = WF in all display modes except format 1 for 8-bit single color panel.
* Pin 77 = XSCL2 in format 1 for 8-bit single color panel.

■ **SED1353D0A PIN OUT**

Chip Size   =   5.030 mm x 5.030 mm
Chip Thickness =   0.400 mm
Pad Size   =   0.090 mm x 0.090 mm
Pad Pitch   =   0.126 mm (Min.)

* Pad 97 = WF in all display modes except format 1 for 8-bit single color panel.
* Pad 97 = XSCL2 in format 1 for 8-bit single color panel.

PAD Coordinates

Pad No.	Pin Name	Pad Center Coordinate		Pad No.	Pin Name	Pad Center Coordinate	
		X	Y			X	Y
1	VSS	-2.165	-2.390	37	RESET	2.390	-1.535
2	---	-2.000	-2.390	38	VA0	2.390	-1.388
3	VDD	-1.840	-2.390	39	VA1	2.390	-1.246
4	DB8	-1.685	-2.390	40	VA2	2.390	-1.106
5	DB9	-1.535	-2.390	41	---	2.390	-0.969
6	DB10	-1.388	-2.390	42	VA3	2.390	-0.835
7	DB11	-1.246	-2.390	43	VA4	2.390	-0.703
8	DB12	-1.106	-2.390	44	---	2.390	-0.573
9	DB13	-0.969	-2.390	45	VA5	2.390	-0.444
10	DB14	-0.835	-2.390	46	VA6	2.390	-0.317
11	DB15	-0.703	-2.390	47	---	2.390	-0.190
12	---	-0.573	-2.390	48	VA7	2.390	-0.063
13	AB0	-0.444	-2.390	49	VA8	2.390	0.063
14	AB1	-0.317	-2.390	50	---	2.390	0.190
15	AB2	-0.190	-2.390	51	VA9	2.390	0.317
16	AB3	-0.063	-2.390	52	VA10	2.390	0.444
17	AB4	0.063	-2.390	53	---	2.390	0.573
18	AB5	0.190	-2.390	54	VD0	2.390	0.703
19	AB6	0.317	-2.390	55	VD1	2.390	0.835
20	AB7	0.444	-2.390	56	---	2.390	0.969
21	---	0.573	-2.390	57	VD2	2.390	1.106
22	AB8	0.703	-2.390	58	VD3	2.390	1.246
23	AB9	0.835	-2.390	59	VD4	2.390	1.388
24	AB10	0.969	-2.390	60	VD5	2.390	1.535
25	AB11	1.106	-2.390	61	VD6	2.390	1.685
26	AB12	1.246	-2.390	62	---	2.390	1.840
27	AB13	1.388	-2.390	63	---	2.390	2.000
28	AB14	1.535	-2.390	64	VD7	2.390	2.165
29	AB15	1.685	-2.390	65	VSS	2.165	2.390
30	AB16	1.840	-2.390	66	---	2.000	2.390
31	---	2.000	-2.390	67	VDD	1.840	2.390
32	AB17	2.165	-2.390	68	VD8	1.685	2.390
33	AB18	2.390	-2.340	69	VD9	1.535	2.390
34	---	2.390	-2.000	70	VD10	1.388	2.390
35	---	2.390	-1.840	71	VD11	1.246	2.390
36	AB19	2.390	-1.685	72	VD12	1.106	2.390

Pad No.	Pin Name	Pad Center Coordinate		Pad No.	Pin Name	Pad Center Coordinate	
		X	Y			X	Y
73	VD13	0.969	2.390	102	VOE#	-2.390	1.388
74	VD14	0.835	2.390	103	IOCS#	-2.390	1.246
75	VD15	0.703	2.390	104	IOW#	-2.390	1.106
76	---	0.573	2.390	105	---	-2.390	0.969
77	VA11	0.444	2.390	106	IOR#	-2.390	0.835
78	VA12	0.317	2.390	107	MEMCS#	-2.390	0.703
79	VA13	0.190	2.390	108	---	-2.390	0.573
80	VA14	0.063	2.390	109	MEMW#	-2.390	0.444
81	VA15	-0.063	2.390	110	MEMR#	-2.390	0.317
82	VWE#	-0.190	2.390	111	---	-2.390	0.190
83	VCS0#	-0.317	2.390	112	READY	-2.390	0.063
84	VCS1#	-0.444	2.390	113	BHE#	-2.390	-0.063
85	---	-0.573	2.390	114	---	-2.390	-0.190
86	UD3	-0.703	2.390	115	OSC1	-2.390	-0.317
87	UD2	-0.835	2.390	116	OSC2	-2.390	-0.444
88	UD1	-0.969	2.390	117	---	-2.390	-0.573
89	UD0	-1.106	2.390	118	DB0	-2.390	-0.703
90	LD3	-1.246	2.390	119	DB1	-2.390	-0.835
91	LD2	-1.388	2.390	120	---	-2.390	-0.969
92	LD1	-1.535	2.390	121	DB2	-2.390	-1.106
93	LD0	-1.685	2.390	122	DB3	-2.390	-1.246
94	YD	-1.840	2.390	123	DB4	-2.390	-1.388
95	---	-2.000	2.390	124	DB5	-2.390	-1.535
96	LP	-2.340	2.390	125	DB6	-2.390	-1.685
97	WF/XSCL2	-2.390	2.165	126	---	-2.390	-1.840
98	---	-2.390	2.000	127	---	-2.390	-2.000
99	---	-2.390	1.840	128	DB7	-2.390	-2.165
100	XSCL	-2.390	1.685	129	Dummy Pad	2.390	2.390
101	LCDENB	-2.390	1.535	130	Dummy Pad	-2.390	-2.390

■ PIN DESCRIPTION

Key

I	=	Input
O	=	Output
I/O	=	Bidirectional
P	=	Power

Bus Interface

Pin Name	Type	F0A Pin #	F1A Pin #	D0A Pad #	Description
DB0-DB15	I/O	94 - 100, 1, 4 -11	91 - 98, 1 - 8	118-119, 121-125, 128, 4-11	These pins are connected to the system data bus. In 8-bit bus mode, DB8-DB15 must be tied to V_{DD}.
AB0	I	12	9	13	In MC68000 MPU interface, this pin is connected to the Upper Data Strobe (UDS#) pin of MC68000. In other bus interfaces, this pin is connected to the system address bus.
AB1-AB19	I	13 - 31	10 - 28	14-20, 22-30, 32-33, 36	These pins are connected to the system address bus.
BHE#	I	91	88	113	In MC68000 MPU interface, this pin is connected to the Lower Data Strobe (LDS#) pin of MC68000. In other bus interfaces, this pin is the Byte High Enable input for use with 16-bit system. In 8-bit bus mode, tie BHE# input to V_{DD}.
IOCS#	I	84	81	103	Active low input to select one of fifteen internal registers.
IOW#	I	85	82	104	In MC68000 MPU interface, this pin is connected to the R/W# pin of MC68000. This input pin will define whether the data transfer is a read (active high) or write (active low) cycle. In other bus interfaces, this is the active low input to write data into an internal register.
IOR#	I	86	83	106	In MC68000 MPU interface, this pin is connected to the AS# pin of MC68000. This input pin will indicate a valid address is available on the address bus. In other bus interfaces, this is the active low input to read data from an internal register.
MEMCS#	I	87	84	107	Active low input to indicate the attempt to access the display memory.
MEMW#	I	88	85	109	Active low input to write data to the display memory. This pin should be tied to V_{DD} in an MC68000 MPU interface.
MEMR#	I	89	86	110	Active low input to read data from the display memory. This pin should be tied to V_{DD} in an MC68000 MPU interface.
READY	O	90	87	112	For MC68000 MPU interface, this pin is connected to the DTACK# pin of MC68000 and will be driven low when ever a data transfer is complete. In other bus interfaces, this output is driven low to force the system to insert wait states when needed. READY is placed in a high-impedance (Hi-Z) state after the transfer is completed.
RESET	I	32	29	37	Active high input to force all signals to their inactive states.

Display Memory Interface

Pin Name	Type	F0A Pin #	F1A Pin #	D0A Pad #	Description
VD0-VD15	I/O	44 - 51, 54 - 61	41 - 48, 51 - 58	54-55, 57-61, 64, 68-75	These pins are connected to the display memory data bus. For 16-bit interface, VD0-VD7 are connected to the display memory data bus of even byte addresses and VD8-VD15 are connected to the display memory data bus of odd byte addresses. The output drivers of these pins are tri-stated when RESET is high. On the falling edge of RESET the values of VD0-VD15 are latched into the chip to configure various hardware options.
VA0-VA15	O	33 - 43, 62 - 66	30 - 40 59 - 63	38-40, 42-43, 45-46, 48-49, 51-52, 77-81	These pins are connected to the display memory address bus.
VCS1#	O	69	66	84	Active low chip-select output to the second or odd byte address SRAM.
VCS0#	O	68	65	83	Active low chip-select output to the first or even byte address SRAM.
VWE#	O	67	64	82	Active low output used for writing data to the display memory. This pin is connected to the WE# input of the SRAMs.
VOE#	O	83	80	102	Active low output to enable reading of data from the display memory. This pin is connected to the OE# input of the SRAMs.

LCD Interface

Pin Name	FPDI-1™ Pin Name[a]	Type	F0A Pin #	F1A Pin #	D0A Pad #	Description
UD3-UD0 LD3-LD0	UD3-UD0 LD3-LD0	O	70 - 73 74 - 77	67 - 70 71 - 74	86 - 89 90 - 93	Panel display data bus. The data format depends on the specific panel connected. For 4-bit single panels, these bits are driven 0 (low state).
XSCL	FPSHIFT	O	81	78	100	Display data shift clock. Data is shifted into the LCD X-drivers on the falling edge of this signal.
LP	FPLINE	O	79	76	96	Display data latch clock. The falling edge of this signal is used to latch a row of display data in the LCD X-drivers and to turn on the row driver (Y driver).
WF/XSCL2	MOD FPSHIFT2	O	80	77	97	For format 1 of 8-bit single color panels this is the second shift clock. For all other modes, this is the LCD backplane BIAS signal. This output toggles once every n LP periods, as programmed in AUX[05]
YD	FPFRAME	O	78	75	94	Vertical scanning start pulse. A logic '1' on this signal, sampled by the LCD module on the falling edge of LP, is used by the panel row driver (Y driver) to indicate the start of the vertical frame.
LCDENB	---	O	82	79	101	LCD enable signal output. It can be used externally to turn off the panel supply voltage and backlight.

a. VESA Flat Panel Display Interface Standard (FPDI-1™)

Clock Inputs

Pin Name	Type	F0A Pin #	F1A Pin #	D0A Pad #	Description
OSC1	I	92	89	115	This pin, along with OSC2 is the 2-terminal crystal interface when using a 2-terminal crystal as the clock input. If an external oscillator is used as a clock source, then this pin is the clock input.
OSC2	O	93	90	116	This pin, along with OSC1 is the 2-terminal crystal interface when using a 2-terminal crystal as the clock input. If an external oscillator is used as a clock source, then this pin should be left unconnected.

Power Supply

Pin Name	Type	F0A Pin #	F1A Pin #	D0A Pad #	Description
V_{DD}	P	3, 53	50, 100	3, 67	Voltage supply.
V_{SS}	P	2, 52	49, 99	1, 65	Voltage Ground.

■ SUMMARY OF CONFIGURATION OPTIONS

Pin Name	value on this pin at falling edge of RESET is used to configure: (1/0)	
	1	0
VD0	16-bit host bus interface	8-bit host bus interface
VD1	Use direct-mapping for I/O accesses	Use indexed mapping for I/O accesses
VD2	MC68000 MPU interface	MPU / Bus interface with memory accesses controlled by a READY (WAIT#) signal
VD3	Swap of high and low data bytes in 16-bit bus interface	No byte swap of high and low data bytes in 16-bit bus interface
VD12-VD4	Select I/O mapping address bits [9:1]. These nine bits are latched on power-up and are compared to the MPU address bits [9-1]. A valid I/O cycle combined with a valid address will enable the internal I/O decoder. Therefore, both types of I/O mapping are limited to even address boundaries to determine either the absolute or indexed I/O address of the first register. Note that a "valid I/O cycle" includes IOCS# being toggled low.	
VD15-VD13	Select memory mapping address bits [3:1] These three bits are latched on power-up and are compared to the MPU address bits [19-17]. A valid memory cycle combined with a valid address will enable the internal memory decoder. As only the three most significant bits of the address are compared, the maximum amount of memory supported is 128K bytes. Note that a "valid memory cycle" includes MEMCS# being toggled low. When using 128K byte memory it must be mapped at an even address such that all 128K bytes is available without a change in state on A17, as this would invalidate the internal compare logic.	

Example: If an ISA bus (no byte swap) with memory segment "A" and I/O location 300h are used, the corresponding settings of VD15-VD0 would be:

Pin Name	8-Bit ISA Bus		16-Bit ISA Bus	
	Index Register	Direct Mapping	Index Register	Direct Mapping
VD0	0	0	1	1
VD1	0	1	0	1
VD2	0	0	0	0
VD3	0	0	0	0
VD12-VD4	11 0000 000	11 0000 xxx	11 0000 000	11 0000 xxx
VD15-VD13	101	101	101	101

Where x = don't care; 1 = connected to pull-up resistor; 0 = not connected to pull-up resistor

■ MONOCHROME PASSIVE STN LCD PANEL INTERFACE
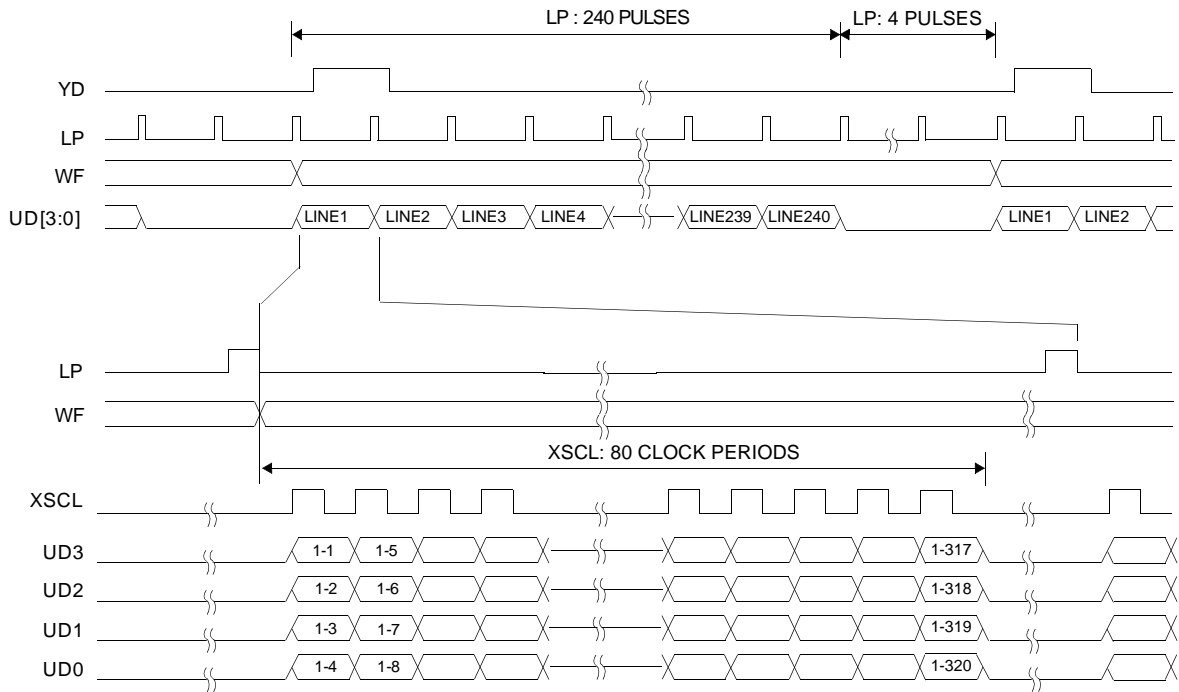
4-Bit Single Panel

Example Timing for a 320x240 single panel

■ **MONOCHROME PASSIVE STN LCD PANEL INTERFACE**
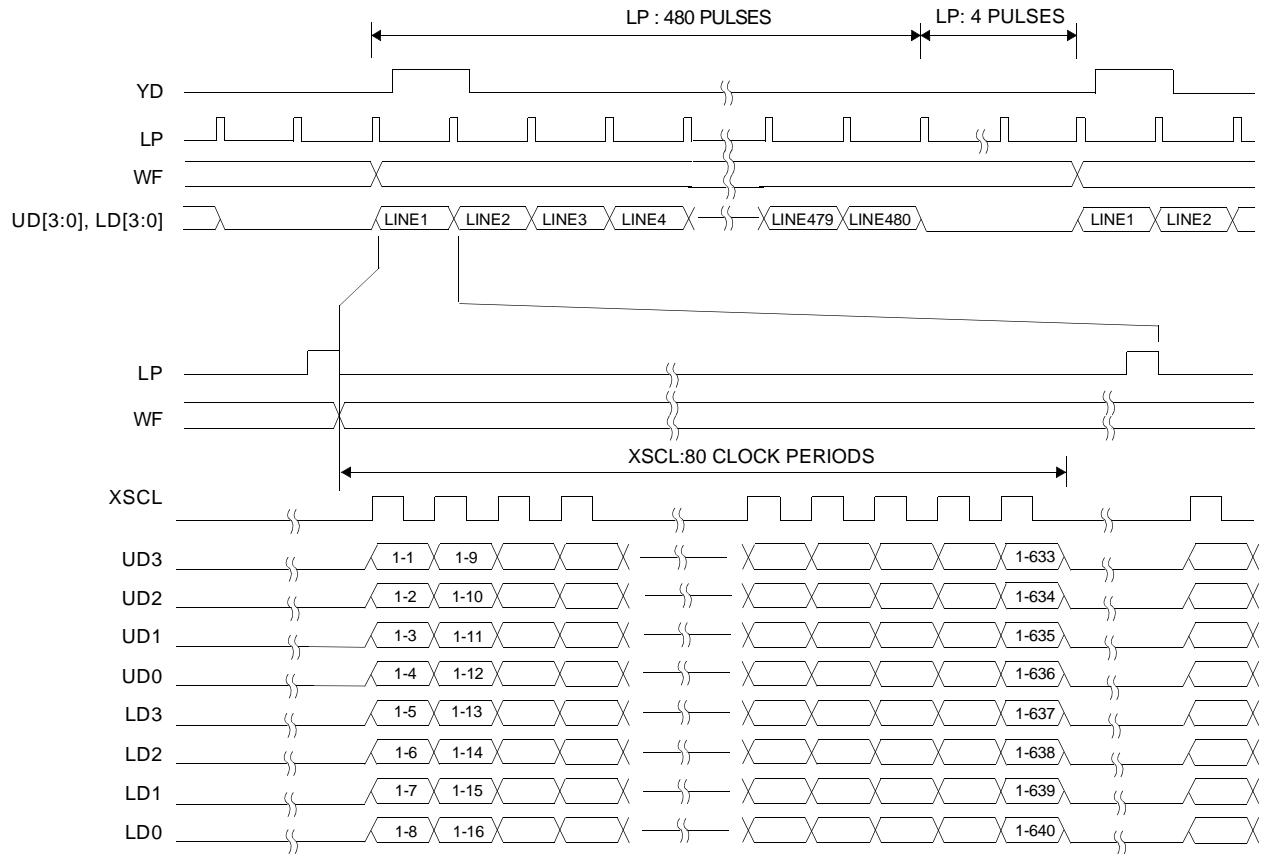
8-Bit Single Panel

Example timing for a 640x480 panel

■ MONOCHROME PASSIVE STN LCD PANEL INTERFACE
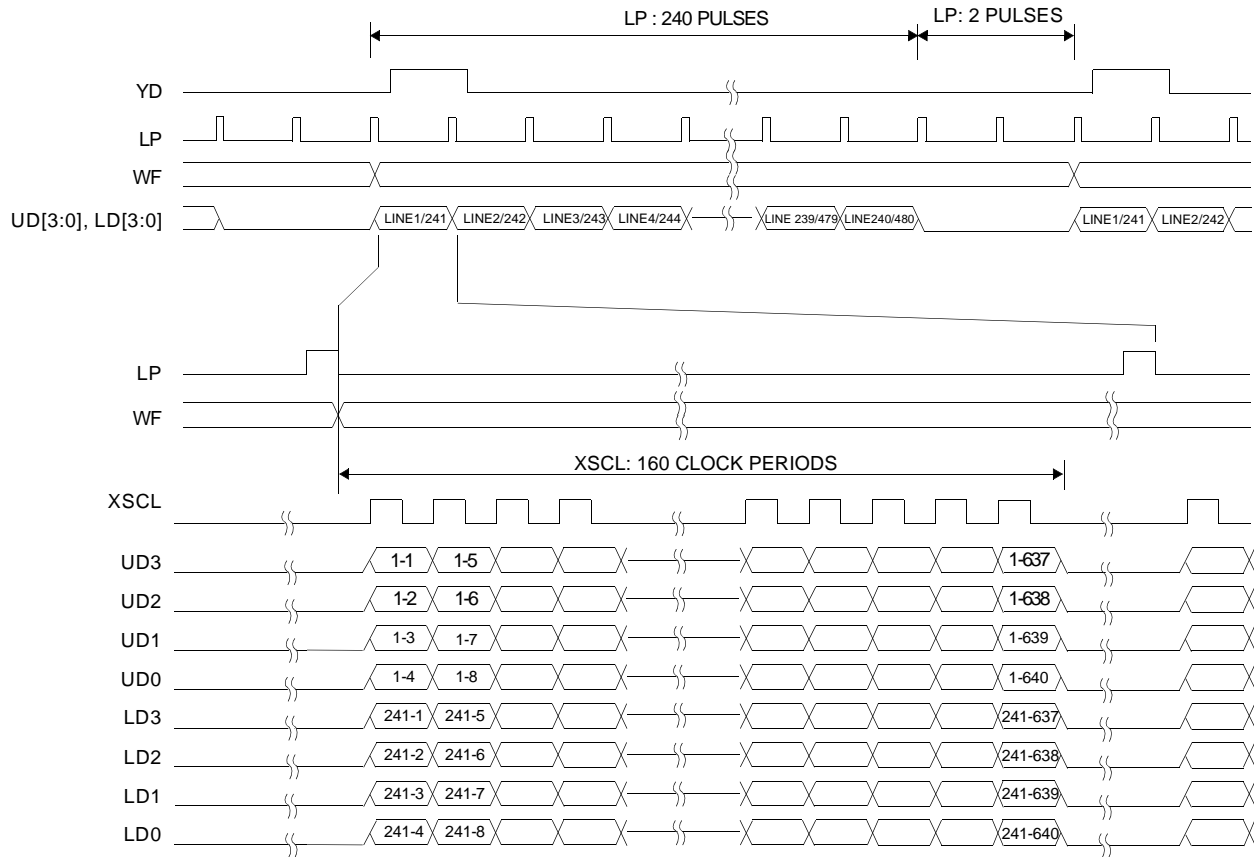
8-Bit Dual Panel

Example timing for a 640x480 panel

■ COLOR PASSIVE STN LCD PANEL INTERFACE

4-Bit Single Panel

Example timing for a 320x240 panel
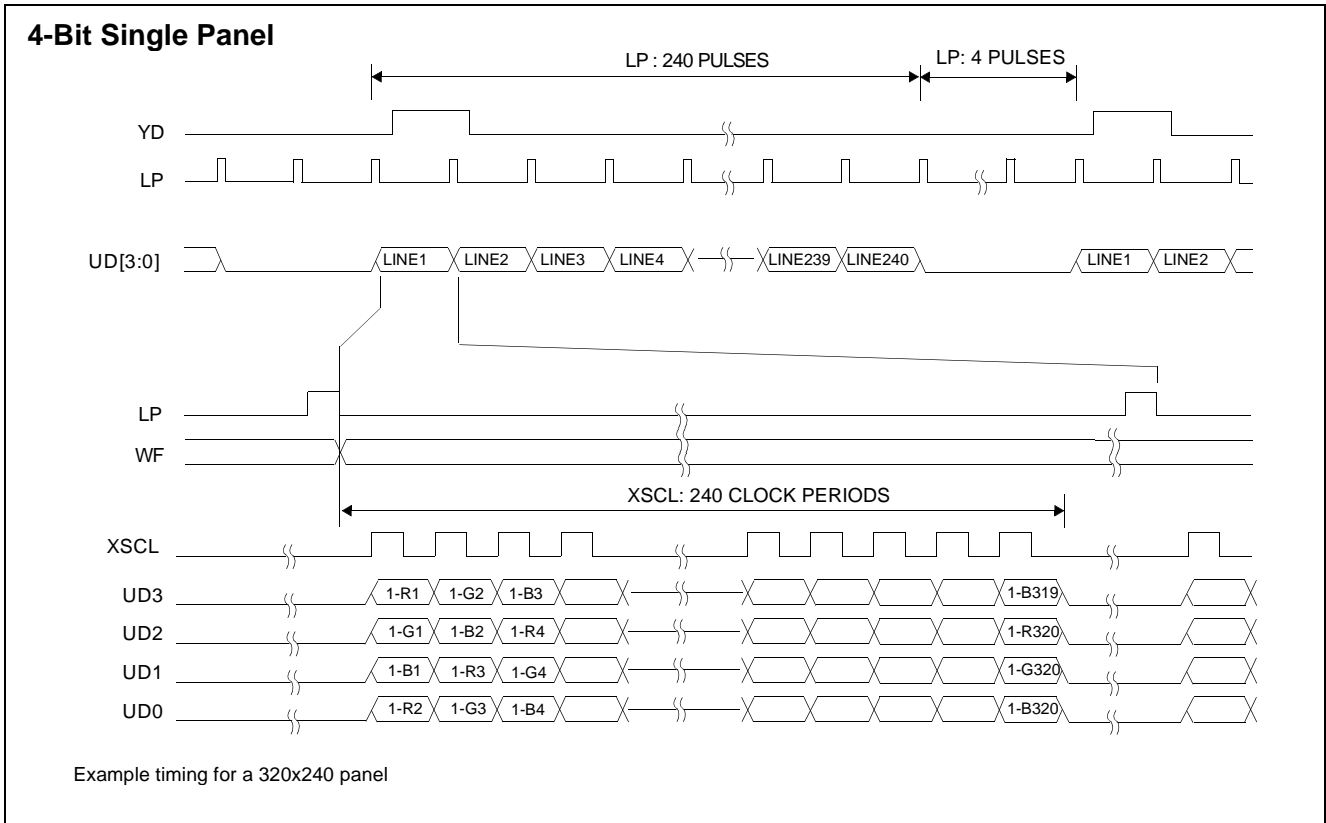
■ COLOR PASSIVE STN LCD PANEL INTERFACE
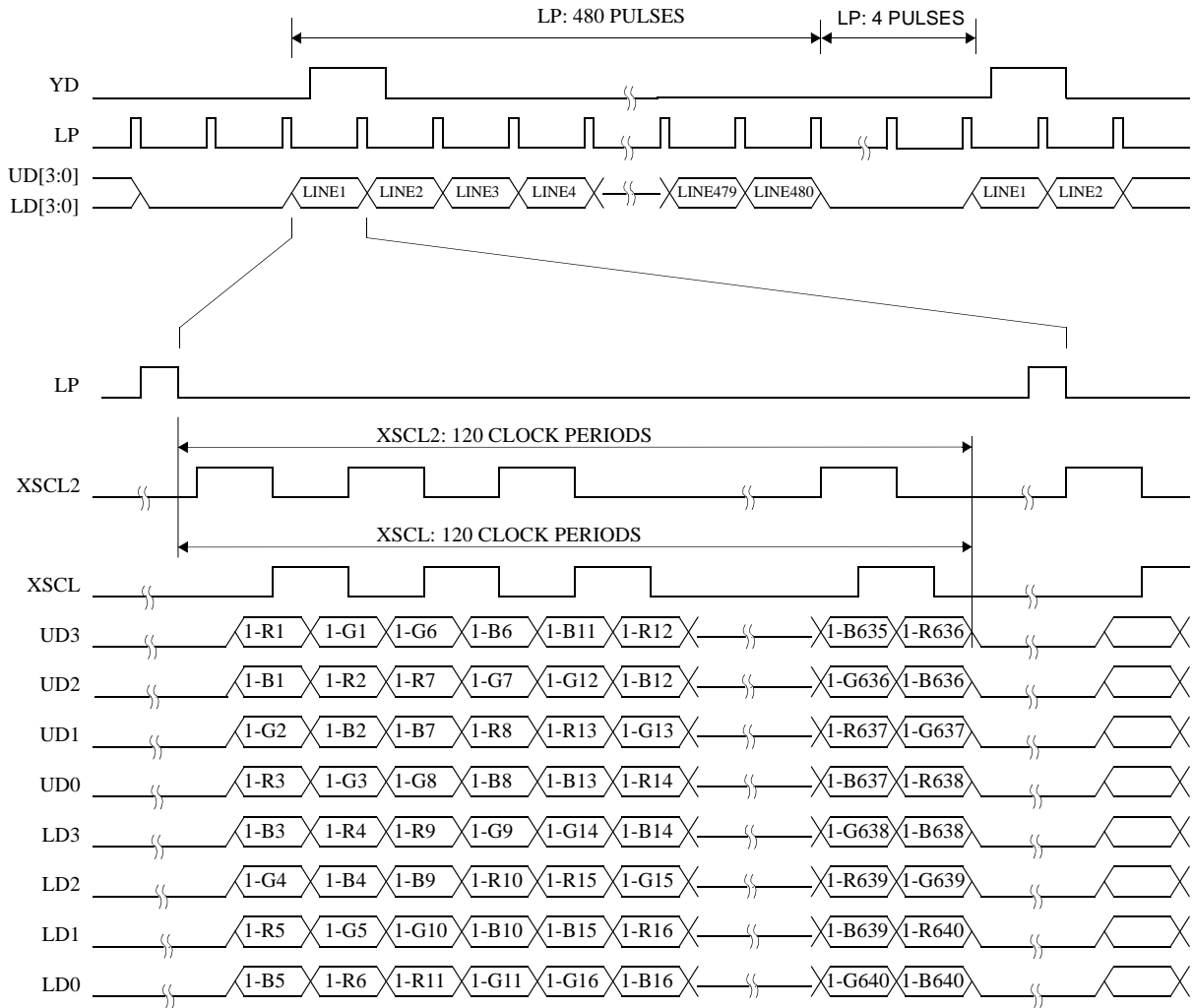
8-Bit Single Panel - Format 1

Example timing for a 640x480 panel

■ COLOR PASSIVE STN LCD PANEL INTERFACE

8-Bit Single Panel - Format 2
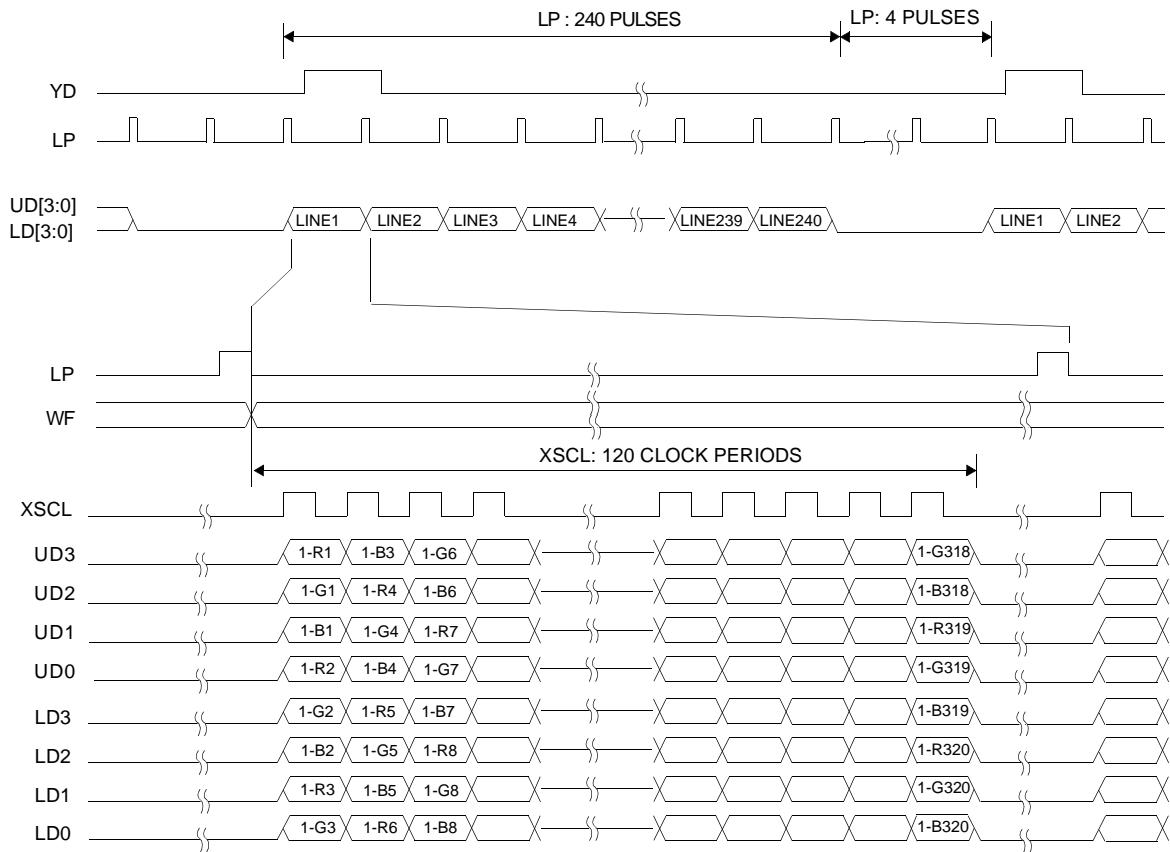
Example timing for a 320x240 panel

■ **COLOR PASSIVE STN LCD PANEL INTERFACE**
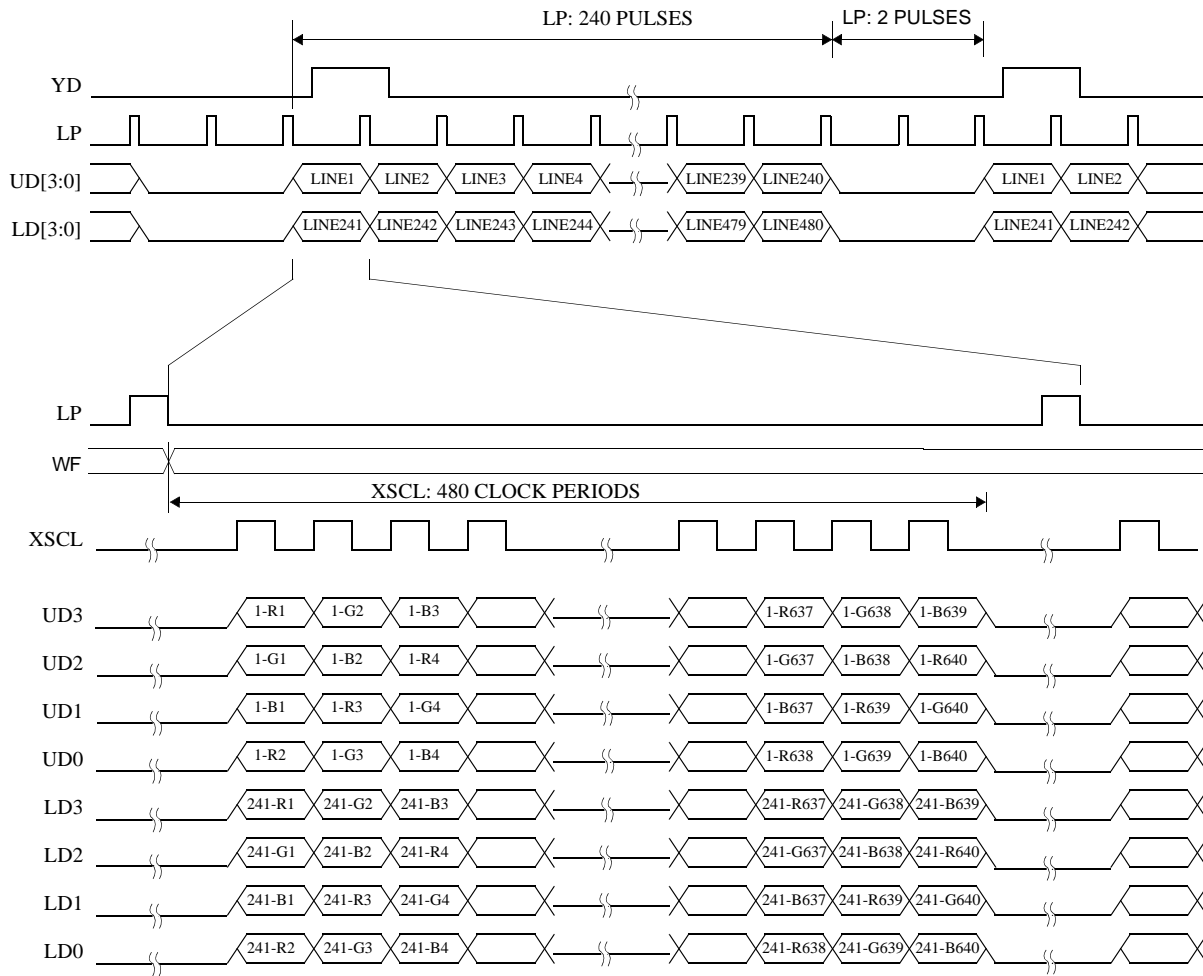
8-Bit Dual Panel

Example timing for a 640x480 panel

■ COLOR PASSIVE STN LCD PANEL INTERFACE

16-Bit Single Panel With External Circuit
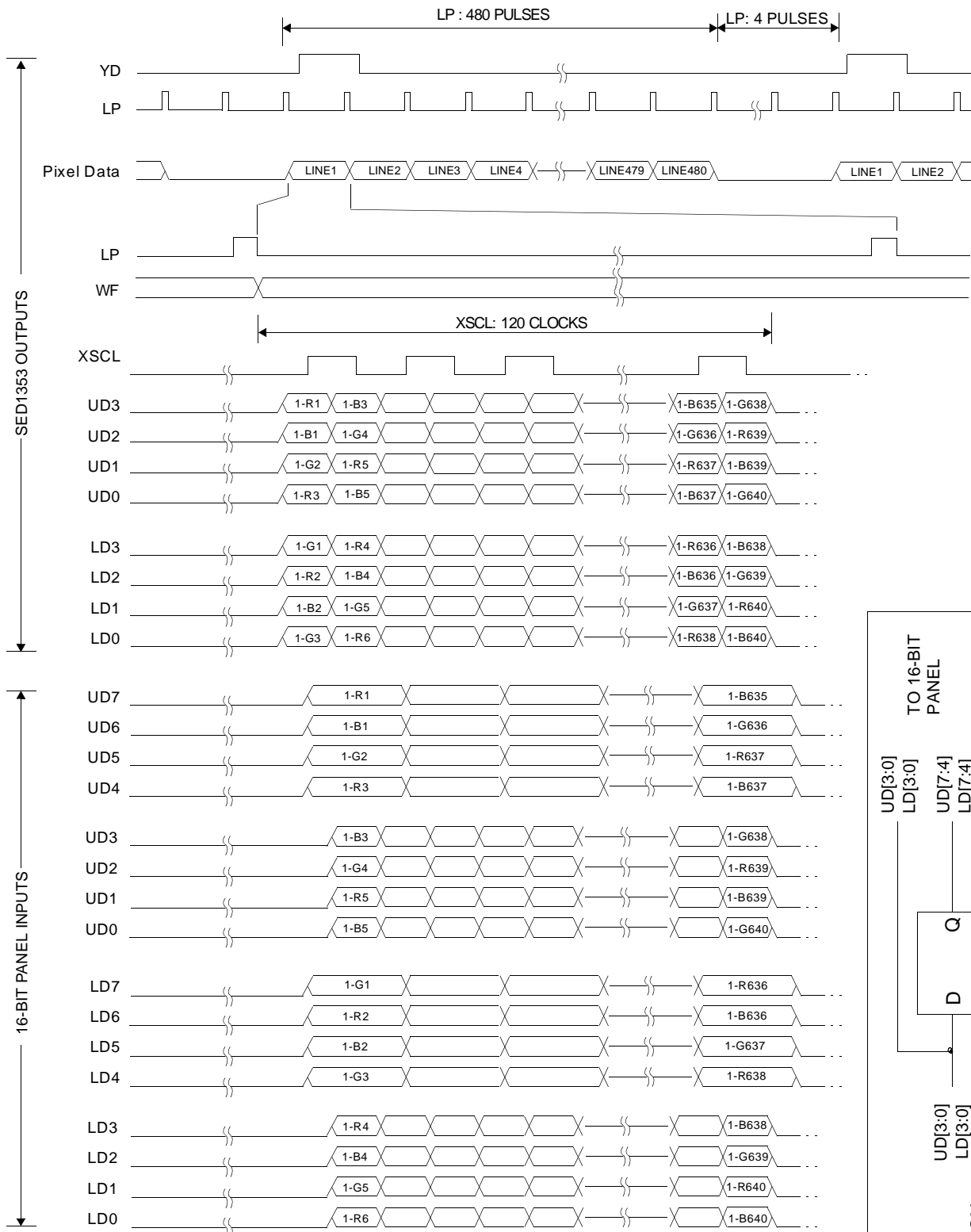
Example timing for a 640x480 panel
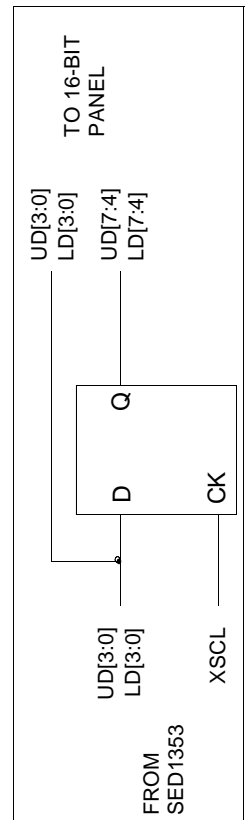
■ **COLOR PASSIVE STN LCD PANEL INTERFACE**

16-Bit Dual Panel With External Circuit
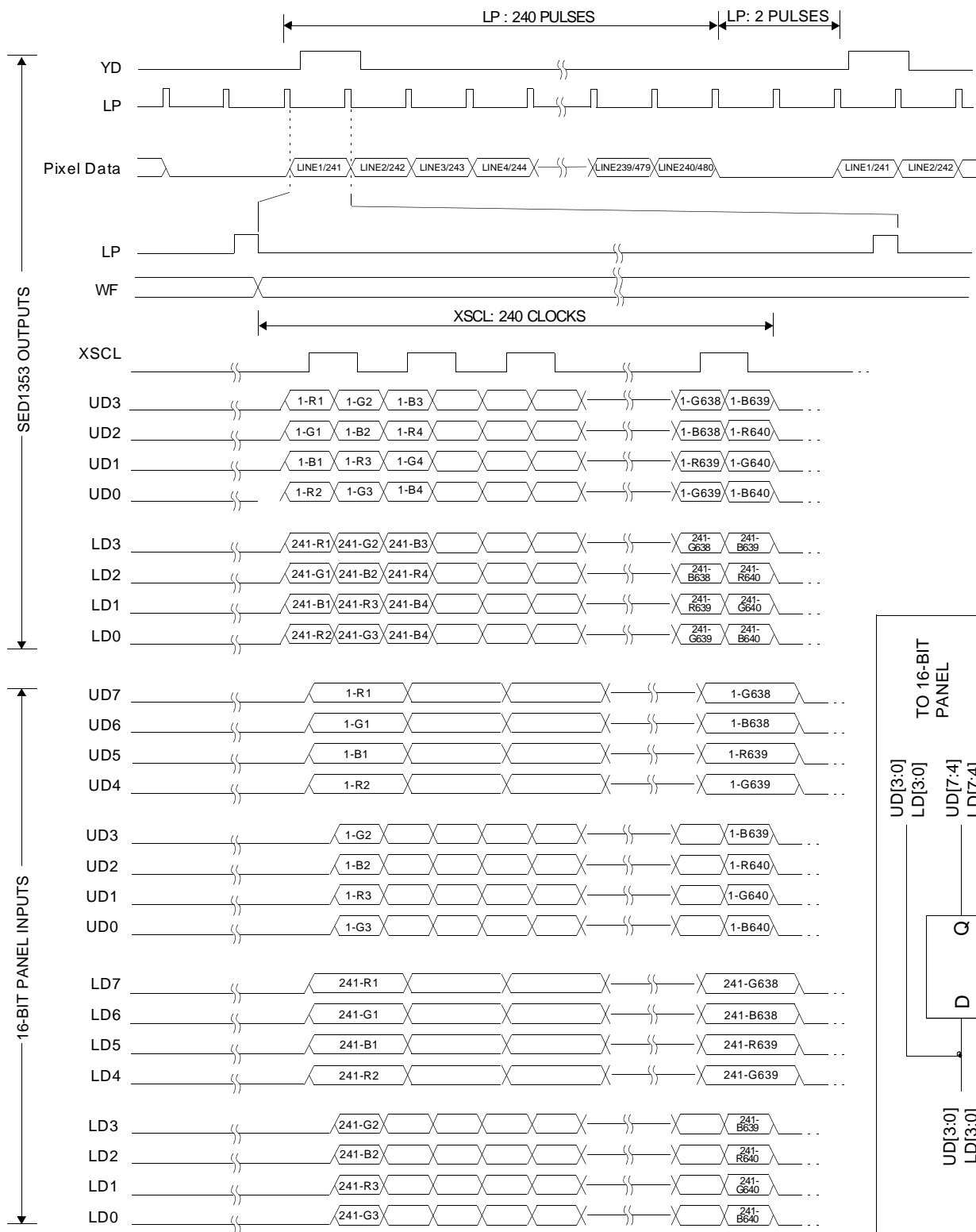
Example timing for a 640x480 panel
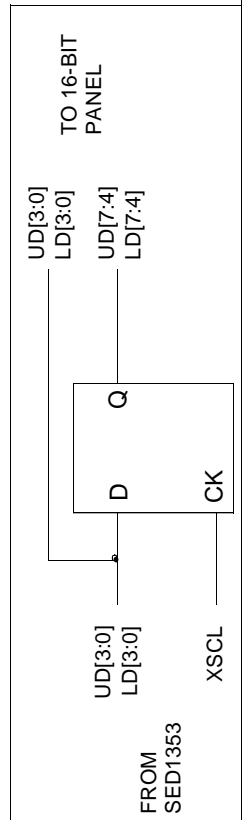
■ **PACKAGE DIMENSIONS: SED1353F0A**

QFP5-100PIN-S2
(SED1353F0A)

All dimensions in mm

Actual Size
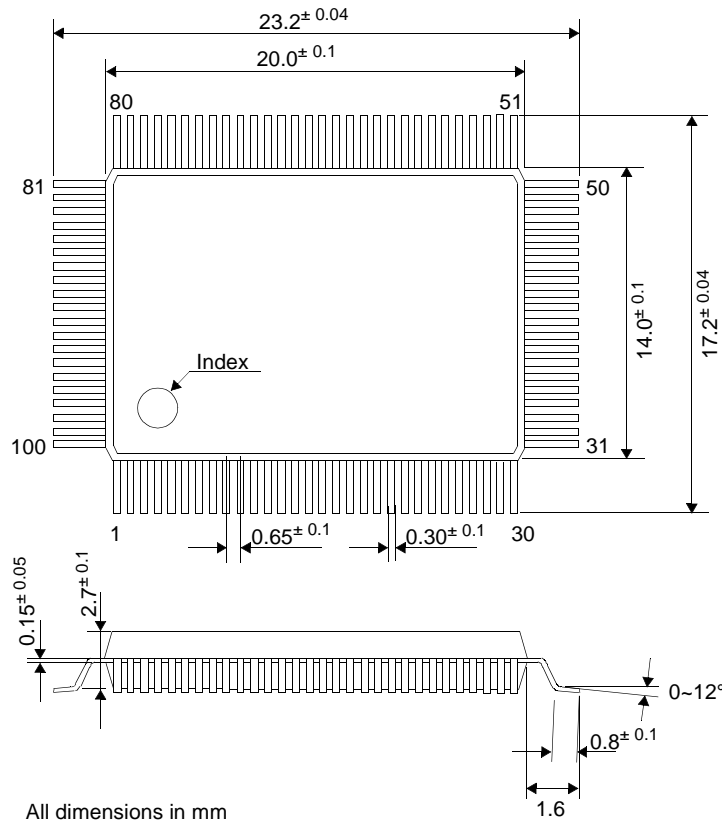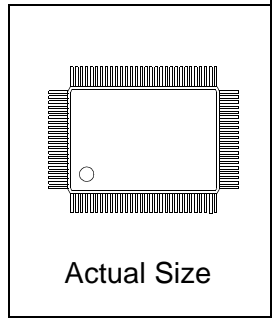
■ **PACKAGE DIMENSIONS: SED1353F1A**

QFP15-100PIN-STD
(SED1353F1A)

All dimensions in mm

Actual Size
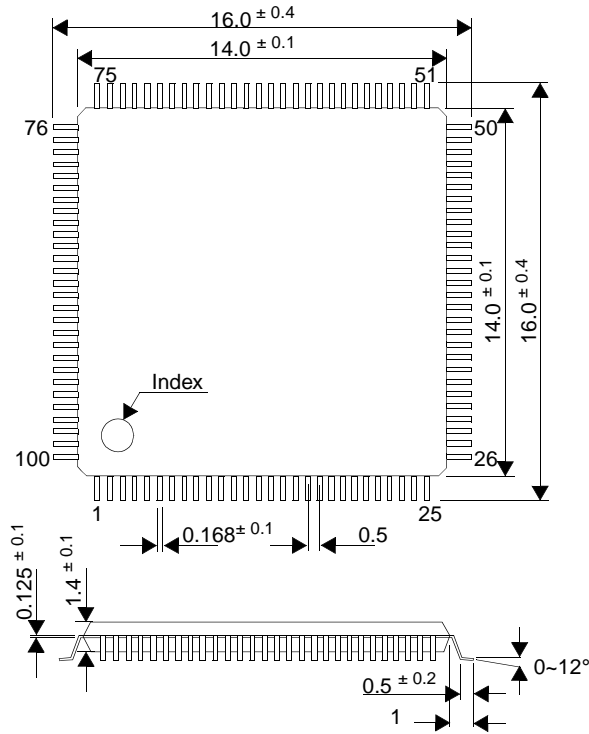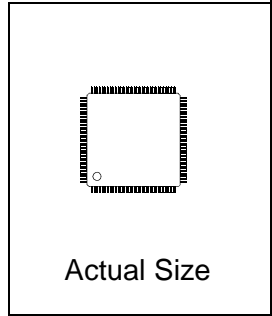
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- Evaluation/Demonstration Board Manual

Evaluation/Demonstration Board
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- Schematic of Evaluation/Demonstration Board
- Parts List
- Installation Guide
- CPU Independent Software Utilities
- Evaluation Software
- Windows CE Display Driver

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